Texas Instruments Semiconductor Products
Conflict Minerals Policy Statement

Texas Instruments (TI) is deeply concerned by reports that profits from the sale of certain metals mined in the Democratic Republic of the Congo (DRC) or adjoining countries has helped fuel war and human rights violations in the eastern Congo. Section 1502 of the Dodd-Frank Wall Street Reform and Consumer Protection Act (the Act) enacted in July 2010 imposes new supply chain reporting requirements on publicly traded companies to promote transparency and consumer awareness regarding the use of "conflict minerals" columbite-tantalite (coltan), cassiterite, gold, wolframite, or their derivatives (tantalum, tin, gold and tungsten) that directly or indirectly finance or benefit armed groups in that region.

As directed by the Act, the U.S. Securities and Exchange Commission (SEC) has adopted rules requiring publicly traded companies to disclose whether they use tantalum, tin, gold and tungsten that originated in the DRC and if so, to issue a report identifying their products that are not conflict free and their due diligence efforts to determine the source and chain of custody of the metals. Conflict free means the product does not contain tantalum, tin, gold and tungsten that directly or indirectly finances or benefits armed groups in the DRC or an adjoining country. In addition, governments around the world are developing policies related to supply chain due diligence of these metals.

TI supports efforts to eliminate the use of tantalum, tin, gold and tungsten from improper sources that could promote such serious problems in the DRC and adjoining countries.

TI, like many companies in the semiconductor and consumer electronic industries, uses tantalum, tin, gold and tungsten to manufacture semiconductor devices and consumer electronic products. Each of these metals has specific electrical properties which are necessary for the function of our products.

TI has been working closely with the Electronics Industry Citizenship Coalition (EICC) and the Global eSustainability Initiative (GeSI) extractives work group and our direct suppliers to trace newly mined minerals back to their origin in order to ensure responsible sourcing. As tracing methods evolve, we are incorporating appropriate proven methods in our program. Our participation in the Organization for Economic Cooperation and Development (OECD) Pilot Implementation program has helped TI design our program with intent to conform in all material respects with the framework in the OECD Due Diligence Guidance for Responsible Supply Chains of Minerals from Conflict-Affected and High-Risk Areas. (http://www.oecd.org/corporate/mne/mining.htm)

TI requires that suppliers whose products contain tantalum, tin, gold and tungsten submit this information to TI using the standardized **EICC/GeSI Conflict Minerals Reporting Template** that traces the metals back through the supply chain. TI also supports industry initiatives such as the Conflict Free Smelter (CFS) program to validate responsible and sustainable sources. Our objective is to have a conflict-free supply chain. If TI

becomes aware of a supplier whose supply chain includes metals from a conflict source, TI will take the appropriate actions to remedy the situation in a timely manner, including reassessment of supplier relationships, to achieve that objective. TI expects our suppliers to take similar measures with their suppliers to ensure alignment throughout the supply chain.

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